MLCAD 2023 Call for Papers

5th ACM/IEEE Workshop on Machine Learning for CAD
September 11-13, 2023
Live in Snowbird, Utah!

MLCAD Workshop

The workshop focuses on Machine Learning (ML) for all aspects of CAD and electronic system design. The workshop is sponsored by both the ACM Special Interest Group on Design Automation (SIGDA) and the IEEE Council on Electronic Design Automation (CEDA). The workshop program will have keynote and invited speakers in addition to technical presentations. MLCAD 2023 will be held physically in Snowbird, Utah, starting with a welcome reception in the evening on September 10.

Paper Submission:
July 25, 2023
Notification:
August 5, 2023
Camera Ready Version:
August 20, 2023
Website:
https://mlcad-workshop.org/

Papers should cover one or more aspects of applying ML to enhance CAD of electronic chips and systems. Such aspects include, but are not limited to: algorithms, tools, example applications, benchmarking, data sources and management, and connections between ML and optimization.

Paper Submission

Submissions should be full-length papers of up to six pages (PDF format, double-column, US letter size, using the IEEE format). Submissions must be anonymous to allow a double-blind review process. Submissions exceeding 6 pages will be rejected. Submitted papers must describe original work that has not been published/accepted or is currently under review. We encourage senior researchers as well as Ph.D. students to be part of the workshop.

Workshop Proceedings

Formal shared ACM/IEEE proceedings will be published containing all accepted papers. Accepted papers will be available in both IEEE Xplore Digital Library and ACM Digital Library.

ACM and IEEE policies

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